

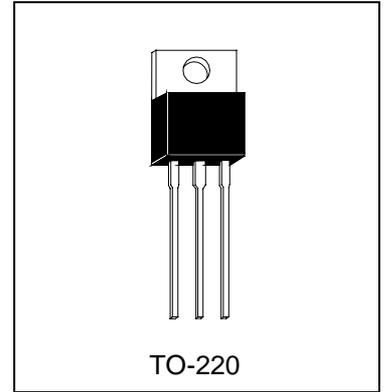


# HMJE13007

NPN EPITAXIAL PLANAR TRANSISTOR

## Description

- High Voltage, High Speed Power Switch
- Switch Regulators
- PWM Inverters and Motor Controls
- Solenoid and Relay Drivers
- Deflection Circuits



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures  
Storage Temperature ..... -50 ~ +150 °C  
Junction Temperature ..... 150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Tc=25°C) ..... 80 W
- Maximum Voltages and Currents (Ta=25°C)  
VCEX Collector to Emitter Voltage ..... 700 V  
VCEO Collector to Emitter Voltage ..... 400 V  
VEBO Emitter to Base Voltage ..... 9 V  
IC Collector Current ..... Continuous 8 A  
IB Base Current ..... Continuous 4 A

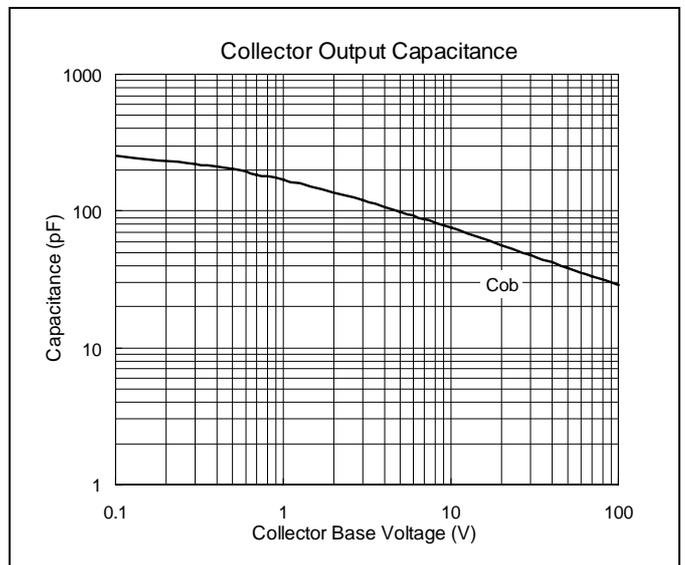
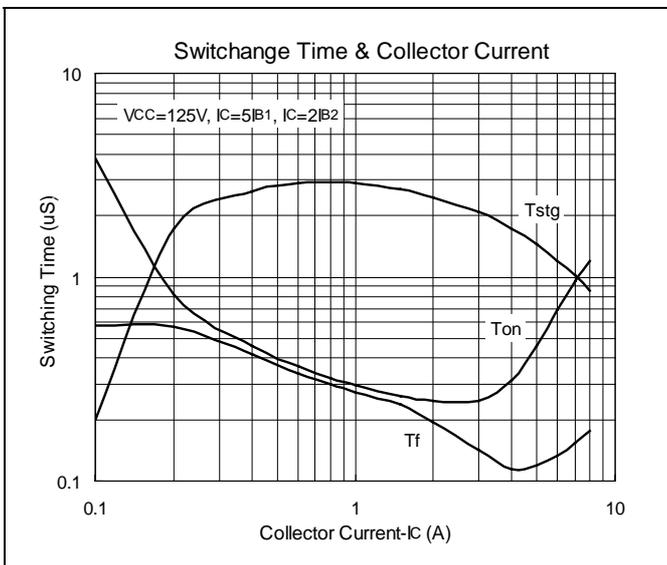
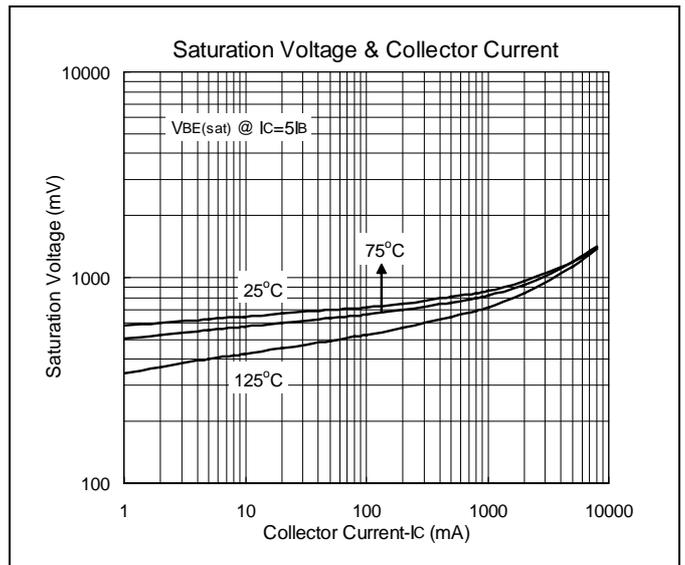
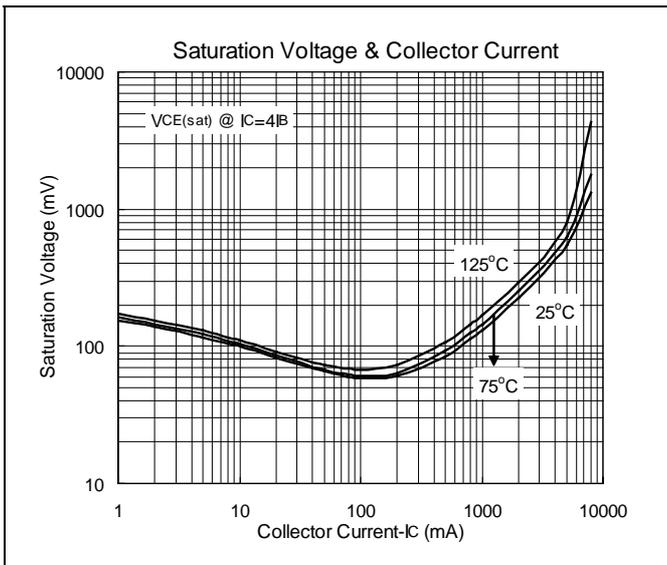
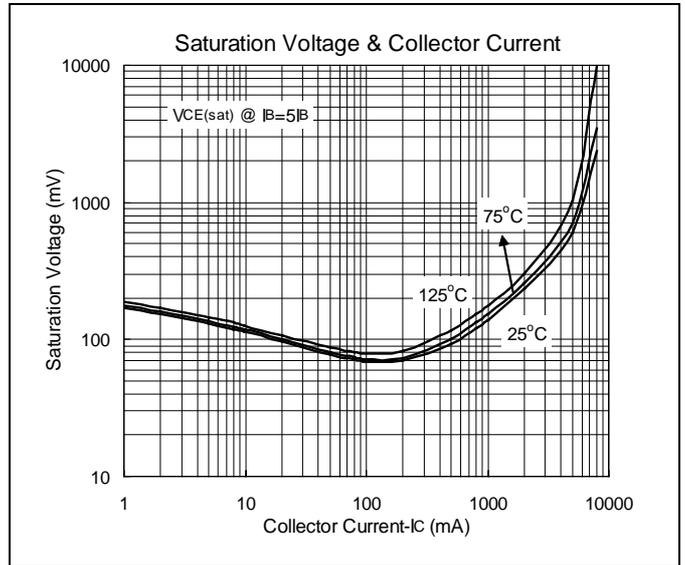
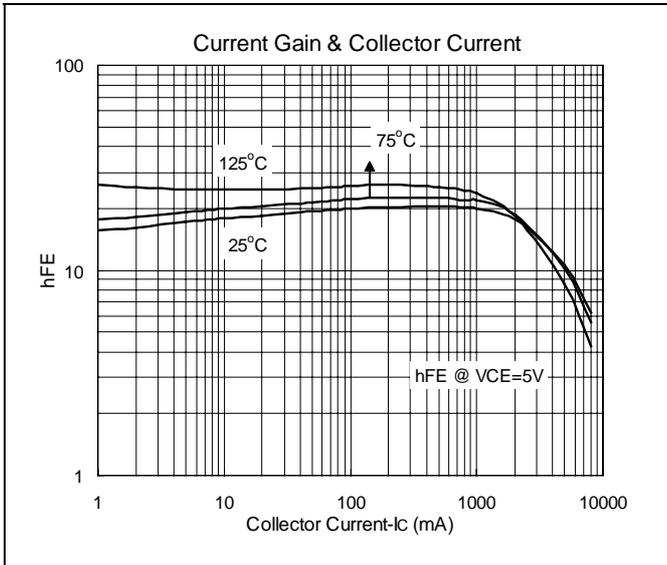
## Characteristics (Ta=25°C)

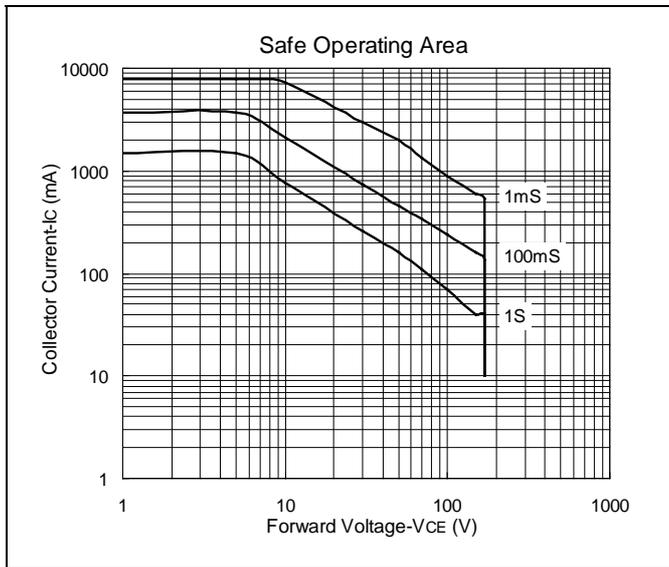
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEX	700	-	-	V	IC=1mA, VBE(off)=1.5V
BVCEO	400	-	-	V	IC=10mA
IEBO	-	-	100	uA	VEB=9V
ICEX	-	-	100	uA	VCE=700V, VBE(off)=1.5V
*VCE(sat)1	-	-	1	V	IC=2A, IB=0.4A
*VCE(sat)2	-	-	2	V	IC=5A, IB=1A
*VCE(sat)3	-	-	3	V	IC=8A, IB=2A
*VBE(sat)	-	-	1.2	V	IC=2A, IB=0.4A
*VBE(sat)	-	-	1.6	V	IC=5A, IB=1A
*hFE1	10	-	-		IC=2A, VCE=5V
*hFE2	6	-	-		IC=5A, VCE=5V
*hFE3	10	-	30		IC=0.5A, VCE=5V

\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



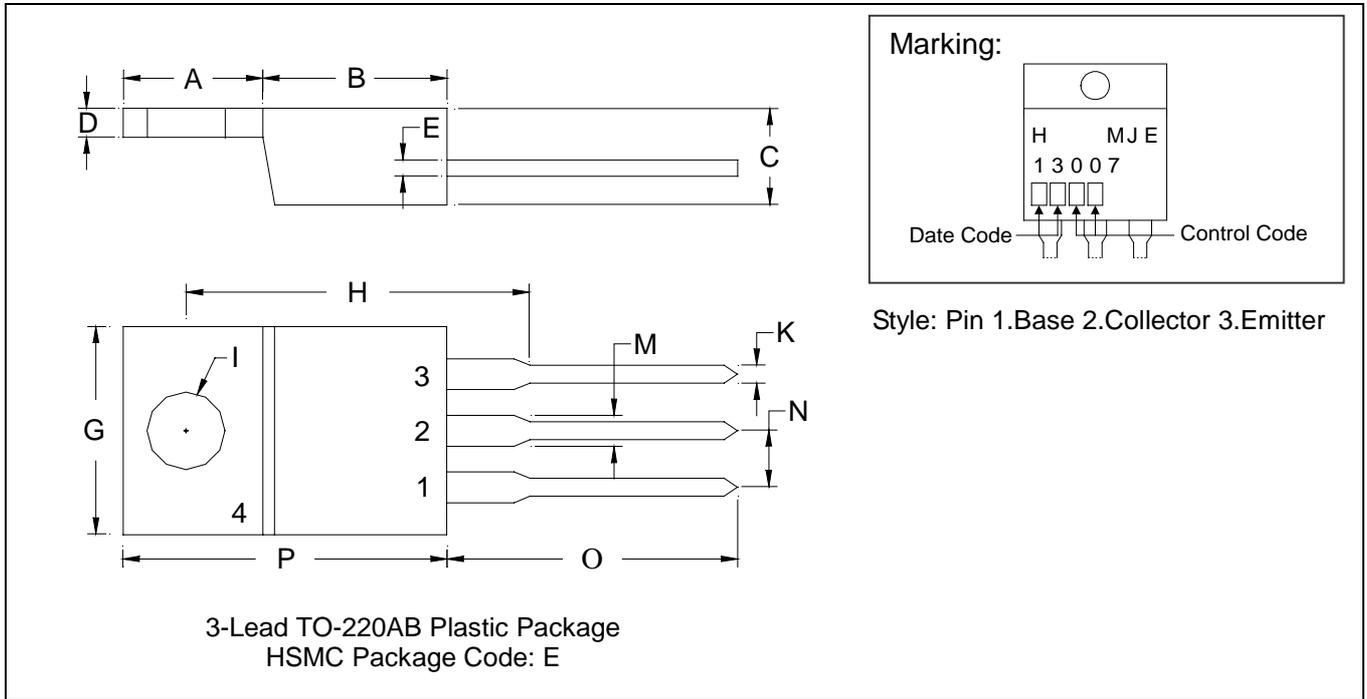
### Characteristics Curve







### TO-220AB Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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